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REINFORCED MICROMODULE

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ABSTRACT (57)

A reinforcement structure to protect an integrated circuit module located within a card-type data carrier or smart card. The reinforcement structure is rigid, having a modulus of elasticity higher than modulus of elasticity of the smart card, and has a thickness dimension that is co-extensive with the thickness dimension of the smart card. The reinforcement structure is provided with a cavity for housing the integrated circuit module. In a preferred embodiment, the reinforcement structure is constructed of thermally and electrically conductive material that is castable or formable to facilitate integration of additional electronic circuit elements therein. In another embodiment, the reinforcement structure is configured in the shape of a SIMM card and is used in place of the normally flexible plastic SIMM card body.

45 Claims, 4 Drawing Sheets

